IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Xian J. Ning

Attorney Docket: 01 P 7422 US 01

Filed: May 14, 2001

Examiner: TBD

Serial No.: TBD

Art Unit: TBD

For: **Design of Lithography Alignment and Overlay Measurement Marks on CMP Finished Damascene Surface**
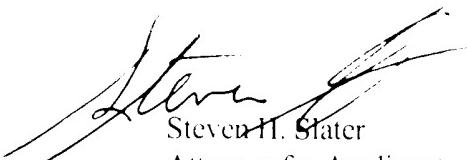
INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner For Patents

Washington, DC 20231

Dear Sir:

Applicant wishes to bring to the attention of the Patent and Trademark Office the information noted on the enclosed PTO-1449 that may be considered material to the examination of the above-identified application.

No fee is due at this time as this statement is being filed with the application.

Respectfully submitted,

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FORM PTO-1449
(REV. 7-80)

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

LIST OF DOCUMENTS CITED BY APPLICANT

(Use several sheets if necessary)

ATTY. DOCKET NO.	SERIAL NO.
01 P 7422 US 01	TBD

APPLICANT

Xian J. Ning

FILING DATE	GROUP
May 14, 2001	TBD

J1033 U.S. PTO
09/854760
05/14/01

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	AL							
	AM							
	AN							

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	AO	Chi-Tzung Wang, et al., Pad Wear Analysis in CMP; 1999 VMIC Conference; 1999 IMIC 109/99/0267(c)
	AP	Srini Raghavan, et al., Elecrochemical Behavior of Copper and Tantalum in Silica Slurries Containing Hydroxylamine, 1999 VMIC Conference; 1999 IMIC 109/99/0619(c)
	AQ	Rajeev Bajaj, et al., Manufacturability Considerations and Approaches for Development of a Copper CMP Process; 1999 VMIC Conference; 1999 IMIC 109/99/0144(c)